

**3V LOW NOISE AMPLIFIER** 

#### Typical Applications

- GSM Handsets
- CDMA Handsets
- TDMA Handsets

- IF or RF Buffer Amplifiers
- Driver Stage for Power Amplifiers
- Oscillator Loop Amplifiers

#### **Product Description**

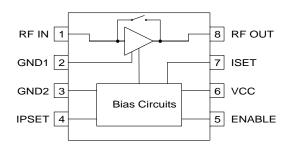
The RF2371 is a general purpose, low-cost, high performance low noise amplifier designed for operation from a 2.7V to 4V supply with low current consumption. The attenuation of the device is controlled when in power down mode, providing a known gain step. The RF2371 is available in a small industry-standard SOT23-8 surface mount package, enabling compact designs which conserve board space. The design features a highly accurate PTAT (Proportional To Absolute Temperature) biasing scheme using bandgap cells.

1.59-1.61 0.15-0.05 0.365 TEXT\* HHH П 0.650 1.44 1.04 2.60 3.00 0.127 3°MAX 0°MIN \*When Pin 1 is in upper left, text reads downward (as shown). 0.35

Package Style: SOT23-8

Optimum Technology Matching® Applied

- Si BJT
- ☐ GaAs HBT
- ☐ GaAs MESFET
- ▼ Si Bi-CMOS SiGe HBT Si CMOS



Functional Block Diagram

#### **Features**

- 700MHz to 2000MHz Operation
- 2.7V to 3.6V Single Supply
- +5dBm Input IP<sub>3</sub> at 3.0mA
- 12dB Gain at 1950MHz
- 1.8dB Noise Figure at 1950MHz
- 17dB Gain Step

#### Ordering Information

RF2371 3V Low Noise Amplifier

RF2371 PCBA Fully Assembled Evaluation Board

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**Absolute Maximum Ratings** 

Parameter	Rating	Unit
Supply Voltage	4.0	V
Supply Current	20	mA
Operating Ambient Temperature	-40 to +85	°C
Storage Temperature	-40 to +150	°C



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Parameter	Specification		Unit	Condition		
Farameter	Min.	Тур.	Max.	Offic	Condition	
Overall					T=27°C, V <sub>CC</sub> =2.7V, V <sub>ISELECT</sub> =0V,	
Overall					V <sub>ENABLE</sub> =2.7V	
Frequency Range		700 to 2000		MHz		
LNA Performance					Freq=1.95GHz	
Gain	10.5	12.5		dB		
Noise Figure		1.6		dB		
Input IP3	+4	+6		dBm	At 2.9mA	
Input P1dB		-14		dBm		
Input VSWR		5:1		dB	(Noise match)	
Output VSWR			1.5:1	dB		
Off Mode Gain		-5.0		dB	V <sub>ENABLE</sub> =0V	
Gain		17		dB	Freq=836MHz	
Noise Figure		1.6		dB		
Input IP3		0		dBm		
Current Control						
Internal Current Setting "ON"		CMOS Low		V	Voltage on ISELECT	
External Current Setting "ON"		CMOS High		V	Voltage on ISELECT	
Current into ISELECT			1	μΑ	V <sub>ISELECT</sub> =2.7V	
Power Control						
Power "ON" Voltage		CMOS High		V	Voltage on ENABLE	
Power "OFF" Voltage		CMOS Low		V	Voltage on ENABLE	
Current into ENABLE			1	μΑ	V <sub>ENABLE</sub> =2.7 V	
Power Supply						
Operating Voltage		2.7 to 3.6		V		
Operating Current		2.9	5	mA	V <sub>CC</sub> =2.7V, Internal current setting	
Leakage Current			1	μΑ	V <sub>ENABLE</sub> =0V	

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RF2371

# Preliminary

Pin	Function	Description	Interface Schematic
1	RF IN	RF input pin. This pin is not internally DC blocked and requires an external blocking capacitor.	
2	GND1	Ground connection for the LNA. Keep traces physically short and connect immediately to ground plane for best performance.	
3	GND2	Ground connection for the bias circuits.	
4	IPSET	This pin selects the internal current setting when CMOS level "low", and the external current setting when this pin is CMOS level "high".	
5	ENABLE	Power down control. This is a CMOS input. When this pin is CMOS "high" the device is enabled. When the level is CMOS "low" the device is shut off and a controlled attenuator is turned on.	
6	VCC	Power supply for the bias circuits.	
7	ISET	This pin sets the current for the device.	
8	RF OUT	RF output pin. Bias for the LNA is provided through this pin, hence it should be connected to VCC through an inductor.	

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## **Application Information**

The RF2371 may be configured to use either the internal current setting or the external current setting. This choice is made by asserting IPSET, pin 4, to CMOS level "low" for the internal current setting or CMOS level "high" for the external current setting.

#### Internal Current Setting

When IPSET is set to CMOS "low", the internal current settings are chosen. This current draw is typically 2.9mA. In this mode, the resistorR1 may be removed from the evaluation board schematic and ISET left floating. The condition for optimal IP3 is to use the internal current setting option and leave the ISET pin open (no connect).

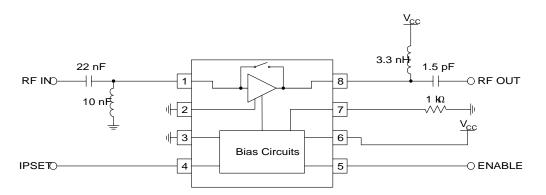
#### External Current Setting

The external current setting is configured by using the series resistor between ISET, pin7, and ground (refer to resistor R1 in evaluation board schematic). The value of the resistor may be changed to permit various operating currents up to a maximum allowable current of 20mA. The table below gives approximate minimum R1 values to allow the 20mA maximum current draw at various operating voltages.

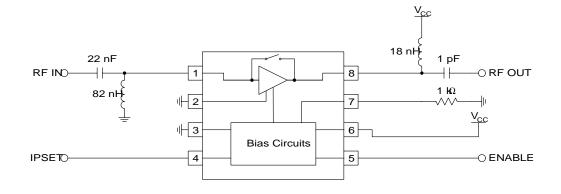
Note: When the internal current setting was selected, the part tested drew 4.4mA, which is higher than typical					
(2.9 mA). Thus values of R1 given vary from part to part.					
V <sub>CC</sub> (V)	Resistor R1 (Ω)	Current Draw (mA)			
2.7	2.4k	20.1			
3.0	2.7k	20.1			
3.3	3.0k	20.0			
3.6	3.3k	19.8			

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# **Application Schematic** 1.95GHz



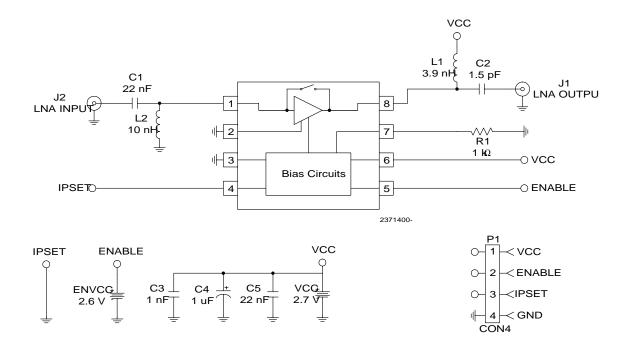
# Application Schematic 836MHz



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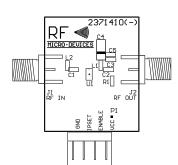
## **Evaluation Board Schematic**

(Download Bill of Materials from www.rfmd.com.)



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# Evaluation Board Layout Board Size 0.833" x 1.009" Board Thickness 0.031", Board Material FR-4





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GENERAL PURPOSE AMPLIFIERS

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